Low Noise Transistor

PNP Silicon

Features

• Pb-Free Packages are Available

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector – Emitter Voltage	V _{CEO}	-50	Vdc
Collector - Base Voltage	V _{CBO}	-50	Vdc
Emitter – Base Voltage	V _{EBO}	-3.0	Vdc
Collector Current – Continuous	Ic	-50	mAdc

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR–5 Board, (Note 1) T _A = 25°C Derate above 25°C	P _D	225 1.8	mW mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	556	°C/W
Total Device Dissipation Alumina Substrate, (Note 2) T _A = 25°C Derate above 25°C	P _D	300 2.4	mW mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	417	°C/W
Junction and Storage Temperature	T _J , T _{stg}	-55 to +150	°C

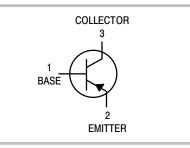
Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

- FR-5 = 1.0 x 0.75 x 0.062 in.
 Alumina = 0.4 x 0.3 x 0.024 in. 99.5% alumina.



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SOT-23 (TO-236) **CASE 318** STYLE 6

MARKING DIAGRAM



2Q = Device Code

M = Date Code*

= Pb-Free Package

(Note: Microdot may be in either location)

*Date Code orientation and/or overbar may vary depending upon manufacturing location.

ORDERING INFORMATION

Device	Package	Shipping [†]
MMBT5087LT1	SOT-23	3,000 / Tape & Reel
MMBT5087LT1G	SOT-23 (Pb-Free)	3,000 / Tape & Reel
MMBT5087LT3	SOT-23	10,000/Tape & Reel
MMBT5087LT3G	SOT-23 (Pb-Free)	10,000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit		
OFF CHARACTERISTICS						
Collector–Emitter Breakdown Voltage $(I_C = -1.0 \text{ mAdc}, I_B = 0)$	V _(BR) CEO	-50	_	Vdc		
Collector–Base Breakdown Voltage ($I_C = -100 \mu Adc, I_E = 0$)	V _(BR) CBO	-50	-	Vdc		
Collector Cutoff Current $(V_{CB} = -10 \text{ Vdc}, I_E = 0)$ $(V_{CB} = -35 \text{ Vdc}, I_E = 0)$	Ісво	- -	-10 -50	nAdc		
ON CHARACTERISTICS	<u> </u>					
DC Current Gain $ \begin{array}{l} (I_C = -100 \; \mu Adc, \; V_{CE} = -5.0 \; Vdc) \\ (I_C = -1.0 \; m Adc, \; V_{CE} = -5.0 \; Vdc) \\ (I_C = -10 \; m Adc, \; V_{CE} = -5.0 \; Vdc) \end{array} $	h _{FE}	250 250 250	800 - -	-		
Collector–Emitter Saturation Voltage (I _C = -10 mAdc, I _B = -1.0 mAdc)	V _{CE(sat)}	_	-0.3	Vdc		
Base–Emitter Saturation Voltage $(I_C = -10 \text{ mAdc}, I_B = -1.0 \text{ mAdc})$	V _{BE(sat)}	_	0.85	Vdc		
SMALL-SIGNAL CHARACTERISTICS	<u> </u>					
Current–Gain — Bandwidth Product ($I_C = -500 \mu Adc, V_{CE} = -5.0 Vdc, f = 20 MHz$)	f _T	40	-	MHz		
Output Capacitance ($V_{CB} = -5.0 \text{ Vdc}$, $I_E = 0$, $f = 1.0 \text{ MHz}$)	C _{obo}	_	4.0	pF		
Small–Signal Current Gain (I _C = -1.0 mAdc, V _{CE} = -5.0 Vdc, f = 1.0 kHz)	h _{fe}	250	900	-		
Noise Figure (I _C = -20 mAdc, V _{CE} = -5.0 Vdc, R _S = 10 k Ω , f = 1.0 kHz) (I _C = -100 μ Adc, V _{CE} = -5.0 Vdc, R _S = 3.0 k Ω , f = 1.0 kHz)	NF	_ _	2.0 2.0	dB		

TYPICAL NOISE CHARACTERISTICS

 $(V_{CE} = -5.0 \text{ Vdc}, T_A = 25^{\circ}C)$

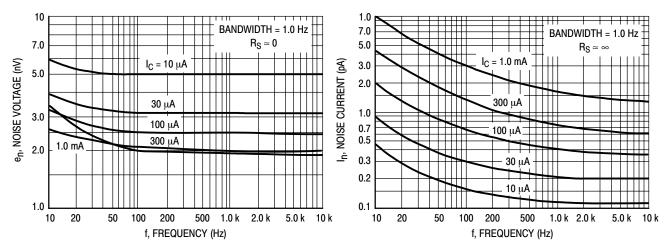


Figure 1. Noise Voltage

Figure 2. Noise Current

NOISE FIGURE CONTOURS

 $(V_{CE} = -5.0 \text{ Vdc}, T_A = 25^{\circ}C)$

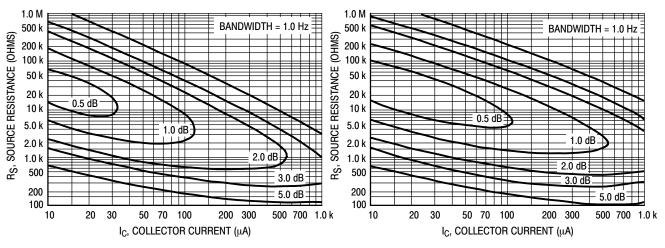


Figure 3. Narrow Band, 100 Hz

Figure 4. Narrow Band, 1.0 kHz

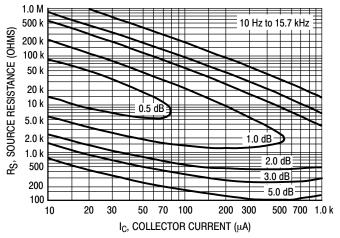


Figure 5. Wideband

Noise Figure is Defined as:

NF =
$$20 \log_{10} \left[\frac{e_n^2 + 4KTR_S + I_n^2 R_S^2}{4KTR_S} \right]^{1/2}$$

en = Noise Voltage of the Transistor referred to the input. (Figure 3)

In = Noise Current of the Transistor referred to the input. (Figure 4)

 $K = Boltzman's Constant (1.38 x 10^{-23} j/^{\circ}K)$

T = Temperature of the Source Resistance (°K)

R_S = Source Resistance (Ohms)

TYPICAL STATIC CHARACTERISTICS

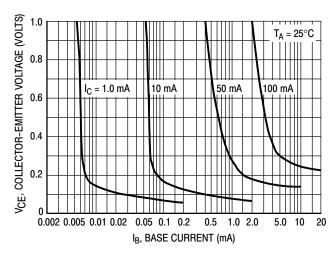


Figure 6. Collector Saturation Region

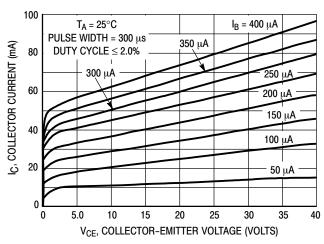


Figure 7. Collector Characteristics

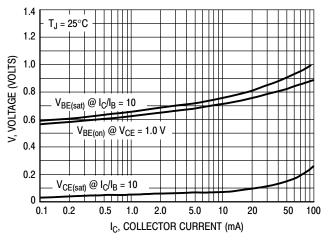


Figure 8. "On" Voltages

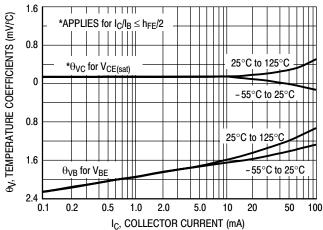
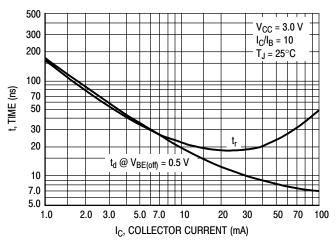


Figure 9. Temperature Coefficients

TYPICAL DYNAMIC CHARACTERISTICS



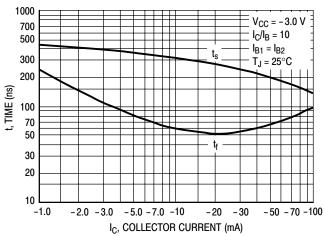
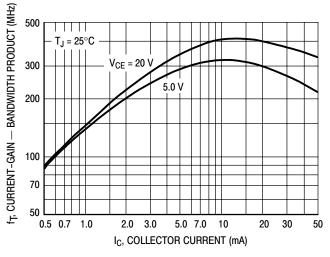


Figure 10. Turn-On Time

Figure 11. Turn-Off Time



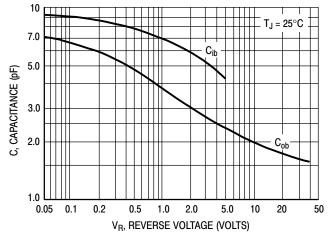


Figure 12. Current-Gain — Bandwidth Product

Figure 13. Capacitance

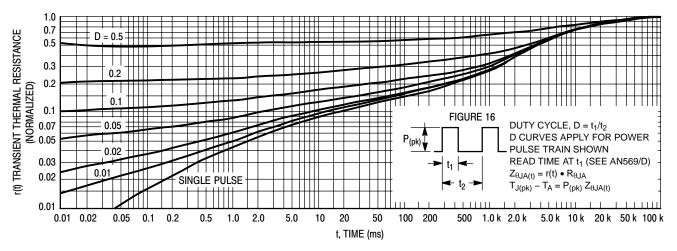


Figure 14. Thermal Response

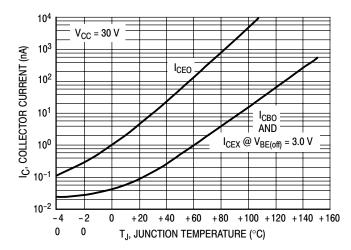


Figure 15. Typical Collector Leakage Current

DESIGN NOTE: USE OF THERMAL RESPONSE DATA

A train of periodical power pulses can be represented by the model as shown in Figure 16. Using the model and the device thermal response the normalized effective transient thermal resistance of Figure 14 was calculated for various duty cycles.

To find $Z_{\theta JA(t)}$, multiply the value obtained from Figure 14 by the steady state value $R_{\theta JA}$.

Example:

Dissipating 2.0 watts peak under the following conditions: $t_1 = 1.0$ ms, $t_2 = 5.0$ ms (D = 0.2)

Using Figure 14 at a pulse width of 1.0 ms and D = 0.2, the reading of r(t) is 0.22.

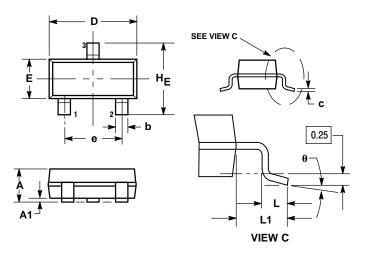
The peak rise in junction temperature is therefore

$$\Delta T = r(t) \times P_{(pk)} \times R_{\theta JA} = 0.22 \times 2.0 \times 200 = 88^{\circ}C.$$

For more information, see ON Semiconductor Application Note AN569/D, available from the Literature Distribution Center or on our website at **www.onsemi.com**.

PACKAGE DIMENSIONS

SOT-23 (TO-236) CASE 318-08 **ISSUE AN**



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER

 - ANSI Y14.5M, 1982.

 2. CONTROLLING DIMENSION: INCH.

 3. MAXIMUM LEAD THICKNESS INCLUDES
 LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF
 - BASE MATERIAL.

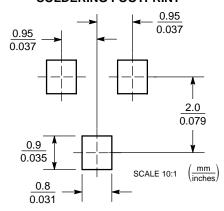
 3. 318-01 THRU -07 AND -09 OBSOLETE,
 NEW STANDARD 318-08.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.89	1.00	1.11	0.035	0.040	0.044
A1	0.01	0.06	0.10	0.001	0.002	0.004
b	0.37	0.44	0.50	0.015	0.018	0.020
С	0.09	0.13	0.18	0.003	0.005	0.007
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
е	1.78	1.90	2.04	0.070	0.075	0.081
L	0.10	0.20	0.30	0.004	0.008	0.012
L1	0.35	0.54	0.69	0.014	0.021	0.029
HE	2.10	2.40	2.64	0.083	0.094	0.104

STYLE 6:

- PIN 1. BASE 2. EMITTER COLLECTOR

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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